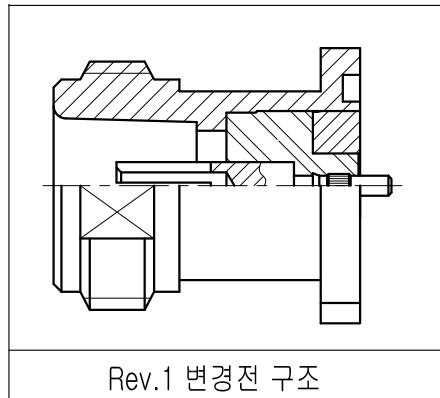
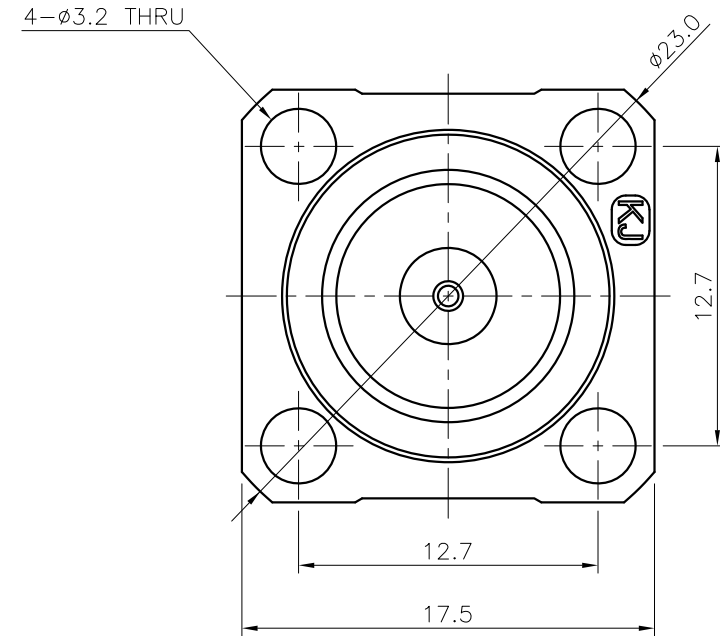
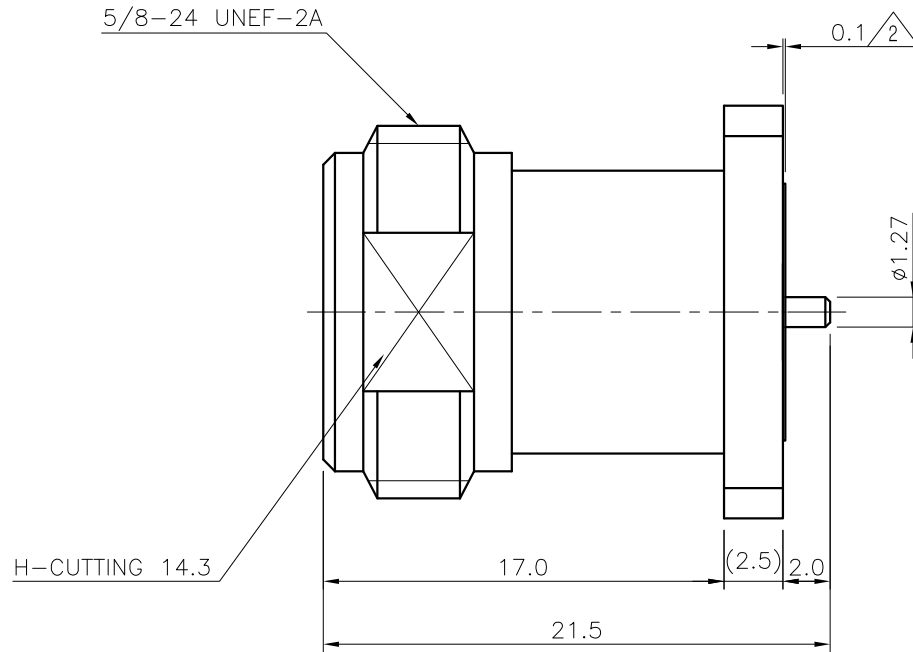
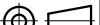


REVISION					
REV	DESCRIPTION		DRAWN	APPR	DATE
IR	Initial Registration		S.Y.EUN	I.C.KIM	2018.09.20.
1	[설변No.202012-0002] O-RING 빠짐 개선 안착부 금형수정		I.C.KIM		2020.12.07.
2	[설변No.202101-0003] O-RING 빠짐 개선 안착부 0.1mm Ground Boss 추가		S.Y.EUN	I.C.KIM	2021.01.20.
3	RING 억지끼움후 돌출부위 감만하여 길이 조정		S.H.KIM		2024.11.08.



3 2 1	4	RING	1	MBsBD C3604BD-F	Nickel Plate	DSR01097-5/4 DSR01097-5/3
	3	INSULATOR	1	TEFLON		DIN02813-N/2
	2	CONTACT	1	BeCu C17300	Gold Plate	DCT03741-5/2
	1	BODY	1	ZnDC	Nickel Plate (3~4µm)	DBD02992-5/3 DBD02992-5/1
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2024. 11. 08.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY				
MATERIAL _____		CHECKED BY			TITLE N50 SOLDER END JS-4H	
		DRAWN BY S.H.KIM				
FINISH _____		SCALE 3/1	UNIT mm		A4	DWG NO. CN03958-7/6
					REVISION 3	SHEET 1 of 1